

2812

AUG 26 2002  
STATEMENT UNDER 37 CFR 1.97(e) ACCOMPANYING  
INFORMATION DISCLOSURE STATEMENT

Docket No.  
END920010002US1

In Re Application Of: Ray et al.

11 / IDS  
e. Willis  
9-10-02

Serial No.  
09/779,812

Filing Date  
2/8/01

Examiner  
Nguyen, Ha T.

Group Art Unit  
2812

Invention: LEAD-FREE SOLDER STRUCTURE AND METHOD FOR HIGH FATIGUE LIFE

TECHNOLOGY CENTER 2800

AUG 27 2002

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TO THE ASSISTANT COMMISSIONER FOR PATENTS:

This is a statement under the provisions of 37 CFR 1.97(e) in the above-identified application.

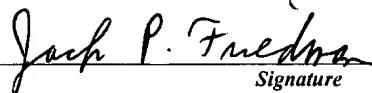
Check applicable statement herebelow:

Statement Under 37 CFR 1.97(e)(1)

Each item of information contained in the accompanying Information Disclosure Statement was first cited in any communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of the Information Disclosure Statement.

Statement Under 37 CFR 1.97(e)(2)

No item of information contained in the accompanying Information Disclosure Statement was cited in a communication from a foreign patent office in a counterpart foreign application, and, to the knowledge of the undersigned person, after making reasonable inquiry, no item of information contained in the accompanying Information Disclosure Statement was known to any individual designated in 37 CFR 1.56(c) more than three months prior to the filing of the Information Disclosure Statement.

  
Signature

Dated: 8/21/02

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